



Material Content Data Sheet



Sales Product Name				IPI70P04P4-09		Issued		25. September 2017	
MA#				MA000797168					
Package				PG-TO262-3-1		Weight*		1571.59 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.074	0.13	0.13	1320	1320	
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		162		
	non noble metal	iron	7439-89-6	0.851	0.05		541		
wire	non noble metal	copper	7440-50-8	849.682	54.08	54.15	540650	541353	
	non noble metal	aluminium	7429-90-5	5.357	0.34	0.34	3409	3409	
encapsulation	organic material	carbon black	1333-86-4	8.844	0.56		5627		
	plastics	epoxy resin	-	97.281	6.19		61900		
leadfinish	inorganic material	silicondioxide	60676-86-0	483.458	30.76	37.51	307624	375151	
	non noble metal	tin	7440-31-5	15.198	0.97	0.97	9670	9670	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	145	146	
solder	non noble metal	tin	7440-31-5	0.040	0.00		26		
	noble metal	silver	7440-22-4	0.050	0.00		32		
heatspreader	non noble metal	lead	7439-92-1	1.923	0.12	0.12	1224	1282	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		20		
*deviation	non noble metal	iron	7439-89-6	0.106	0.01		68		
	non noble metal	copper	7440-50-8	106.210	6.76	6.77	67581	67669	
						Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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